

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

Docket No.: 303.527US2
Filed: August 29, 2000
Examiner: Unknown

Serial No.: 09/649,827
Due Date: N/A
Group Art Unit: Unknown

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

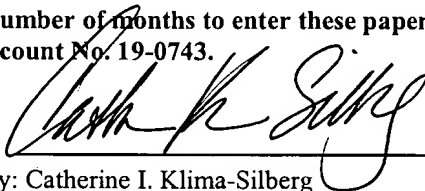
- ☒ A return postcard.
- ☒ Supplemental Preliminary Amendment (5 Pages).
- ☒ A check in the amount of \$108.00 to cover the fee for additional claims as calculated below.
- ☒ Red-line drawing of Figure 5b (1 pg.).
- ☒ Clean Version of Specification Paragraphs (1 pg.).
- ☒ Clean Version of Pending Claims (6 pgs.).

If an additional fee is required due to changes to the claims, the fee has been calculated as follows:

CLAIMS AS AMENDED						
	(1) Claims Remaining After Amendment		(2) Highest Number Previously Paid For	(3) Present Extra	Rate	Fee
TOTAL CLAIMS	30	-	24	6	x 18 =	\$108.00
INDEPENDENT CLAIMS	8	-	8		x 80 =	\$0.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED						\$0.00
TOTAL						\$108.00

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

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By: 
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 19 day of April, 2001.

Name: Amy Morarty

Signature: Amy Morarty

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S/N 09/649,827

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.

Examiner: Unknown

Serial No.: 09/649,827

Group Art Unit: 1733

August 29, 2000

Docket: 303.527US2

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE



Commissioner for Patents
Washington, D.C. 20231

SUPPLEMENTAL PRELIMINARY AMENDMENT

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Before taking up the above-identified application for examination, please enter the following amendments.

IN THE SPECIFICATION

Please substitute the following paragraph that begins on Page 11, line 13 and ends on Page 11, line 20 of the Specification with the paragraph in the appendix entitled Clean Version of Specification Paragraphs. Specific amendments to this paragraph are detailed in the following marked-up paragraph:

[With reference to Figure 5, the] The substrate 12 is placed on an automated conveyor system with the first side 24 facing downwardly. The automated machinery then indexes the substrate 12 to a tape punch station. As shown in Figure 5a, the tape 40 is punched into two strips and the first side 42 is pressed against the die attach area 26 of the substrate 12. The tape 40 is heated momentarily to complete the lamination process. The heat applied is generally below that required to crosslink or set the adhesive. In one embodiment, pressure and 100 deg C heat are applied for 100 ms.

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IN THE DRAWINGS

The drawings were objected to in the Office Action. Applicant is providing red-lined drawings herewith, adding element 14 to Figure 5b. No new matter is entered. Reconsideration of the drawings is respectfully requested.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. Specific amendments to individual claims are detailed in the following marked up set of claims.